



SamHop Microelectronics Corp.

**STB/P60L60**

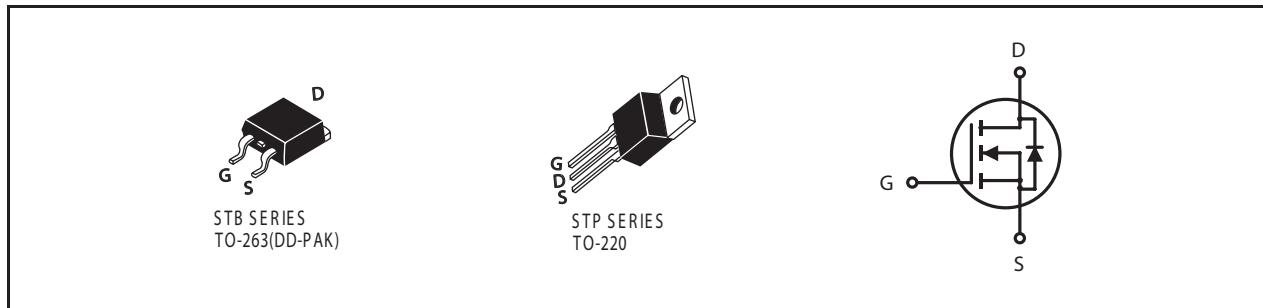
Ver 2.0

## N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Typ
60V	50A	21 @ VGS=10V

### FEATURES

- Super high dense cell design for extremely low RDS(ON).
- High power and current handling capability.
- TO-220 & TO-263 package.



### ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Limit	Units
$V_{DS}$	Drain-Source Voltage		60	V
$V_{GS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Drain Current-Continuous <sup>a</sup>	$T_C=25^\circ\text{C}$	50	A
		$T_C=70^\circ\text{C}$	42	A
$I_{DM}$	-Pulsed <sup>b</sup>		148	A
$E_{AS}$	Avalanche Energy <sup>d</sup>		113	mJ
$P_D$	Maximum Power Dissipation <sup>a</sup>	$T_C=25^\circ\text{C}$	105	W
		$T_C=70^\circ\text{C}$	74	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range		-55 to 175	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.4	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	$^\circ\text{C/W}$

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## ELECTRICAL CHARACTERISTICS (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V			1	A
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1	2	3	V
R <sub>Ds(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =25A		21	25	m ohm
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A		32	42	m ohm
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =25A		26		S
<b>DYNAMIC CHARACTERISTICS</b> <sup>c</sup>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V f=1.0MHz		1830		pF
C <sub>OSS</sub>	Output Capacitance			182		pF
C <sub>RSS</sub>	Reverse Transfer Capacitance			120		pF
<b>SWITCHING CHARACTERISTICS</b> <sup>c</sup>						
t <sub>D(ON)</sub>	Turn-On DelayTime	V <sub>DD</sub> =15V I <sub>D</sub> =1A V <sub>GS</sub> =10V R <sub>GEN</sub> =60 ohm		45		ns
t <sub>r</sub>	Rise Time			70		ns
t <sub>D(OFF)</sub>	Turn-Off DelayTime			125		ns
t <sub>f</sub>	Fall Time			38		ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V,I <sub>D</sub> =25A,V <sub>GS</sub> =10V		28		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V,I <sub>D</sub> =25A, V <sub>GS</sub> =10V		4.5		nC
Q <sub>gd</sub>	Gate-Drain Charge			9		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V,I <sub>s</sub> =10A		0.84	1.3	V
<b>Notes</b>						
a.Surface Mounted on FR4 Board,t ≤ 10sec.						
b.Pulse Test:Pulse Width ≤ 300us, Duty Cycle ≤ 2%.						
c.Guaranteed by design, not subject to production testing.						
d.Starting T <sub>j</sub> =25°C,L=1.25mH,V <sub>DD</sub> = 30V.(See Figure13)						

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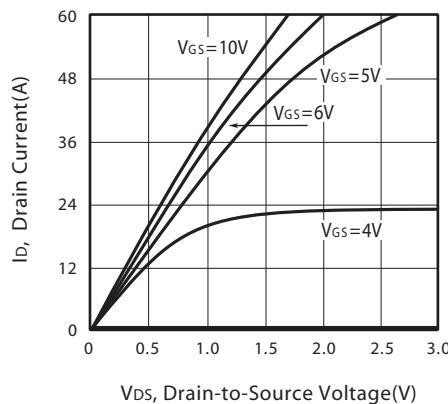


Figure 1. Output Characteristics

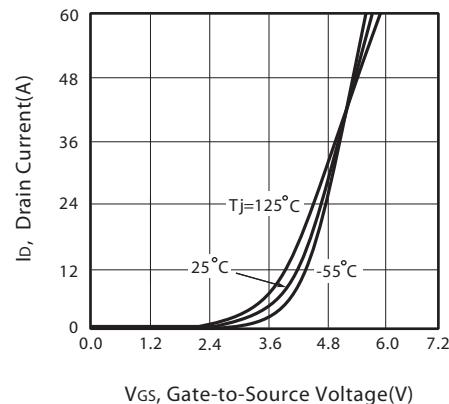


Figure 2. Transfer Characteristics

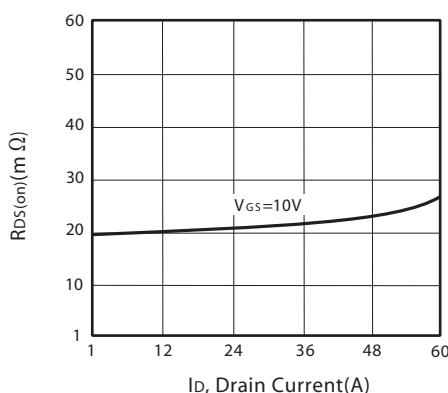


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

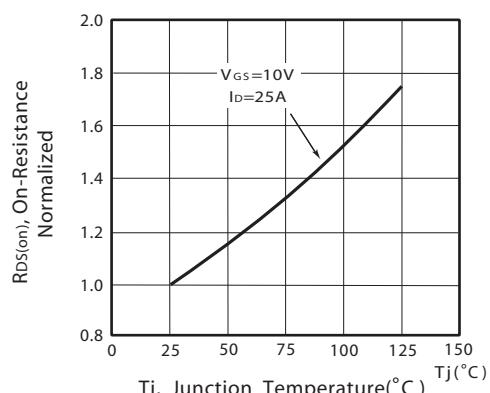


Figure 4. On-Resistance Variation with Drain Current and Temperature

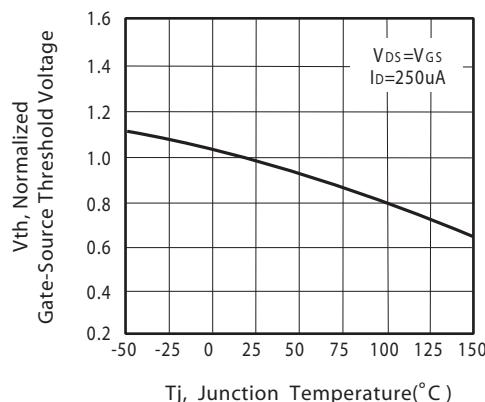


Figure 5. Gate Threshold Variation with Temperature

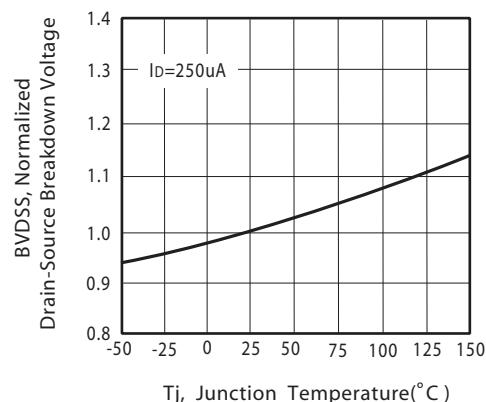
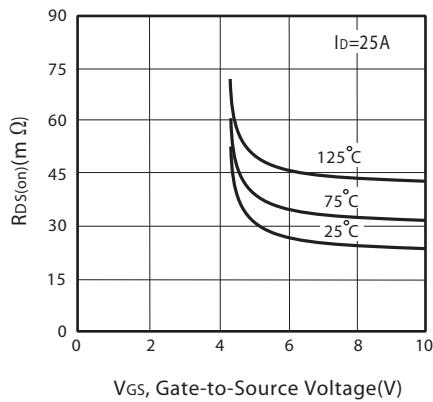


Figure 6. Breakdown Voltage Variation with Temperature

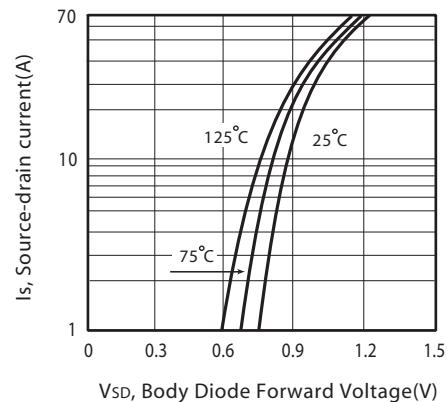
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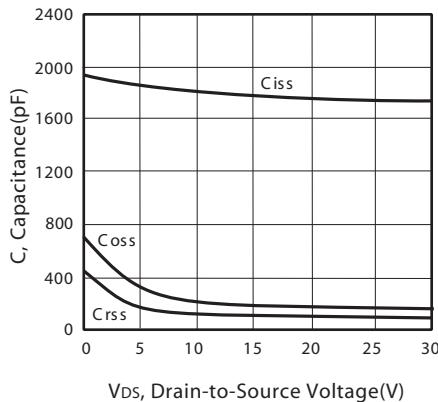
V<sub>GS</sub>, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



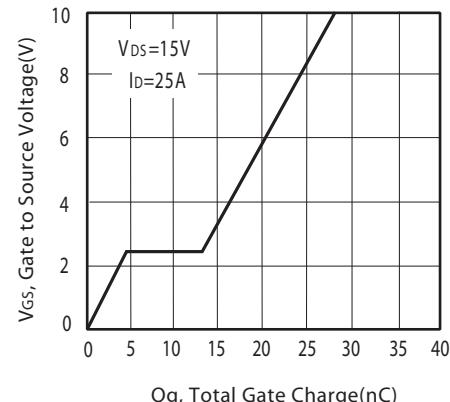
V<sub>SD</sub>, Body Diode Forward Voltage(V)

Figure 8. Body Diode Forward Voltage Variation with Source Current



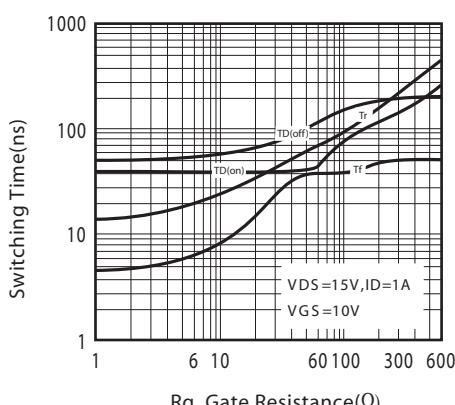
V<sub>DS</sub>, Drain-to-Source Voltage(V)

Figure 9. Capacitance



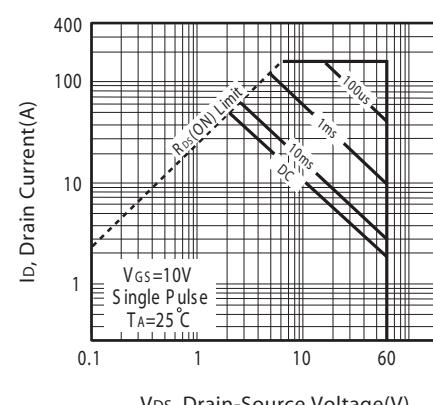
Q<sub>g</sub>, Total Gate Charge(nC)

Figure 10. Gate Charge



R<sub>g</sub>, Gate Resistance(Ω)

Figure 11. switching characteristics

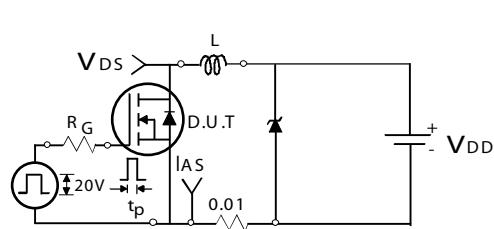


V<sub>DS</sub>, Drain-Source Voltage(V)

Figure 12. Maximum Safe Operating Area

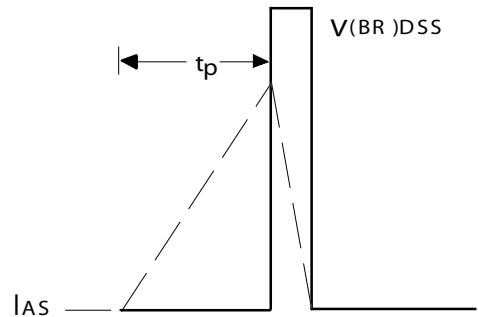
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Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

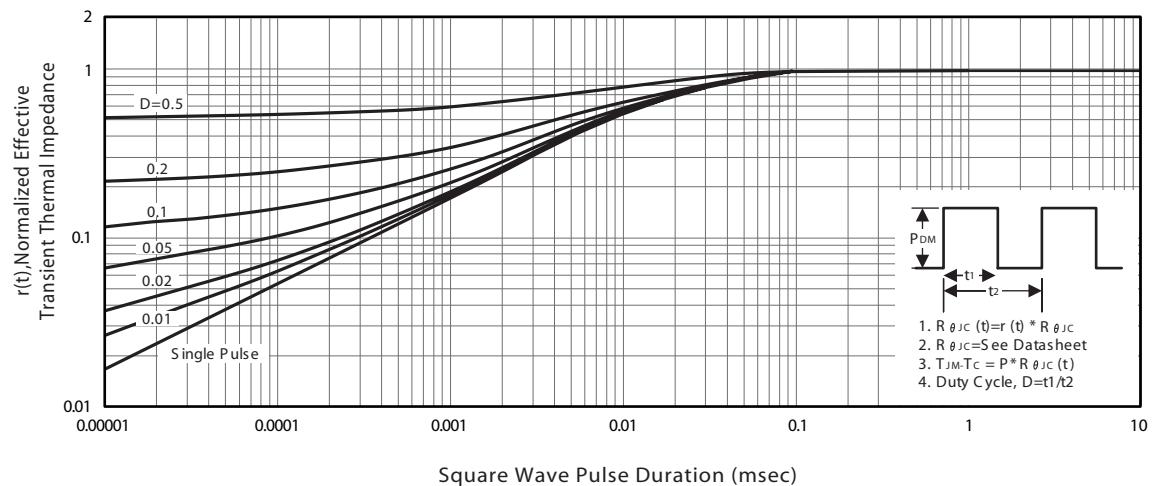
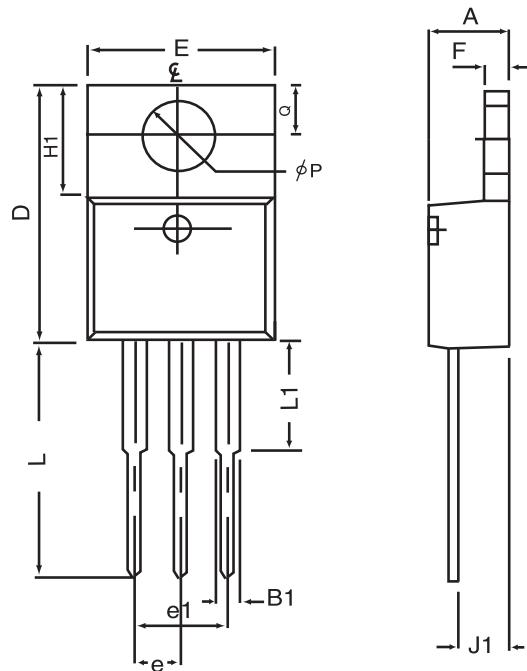


Figure 14. Normalized Thermal Transient Impedance Curve

## PACKAGE OUTLINE DIMENSIONS

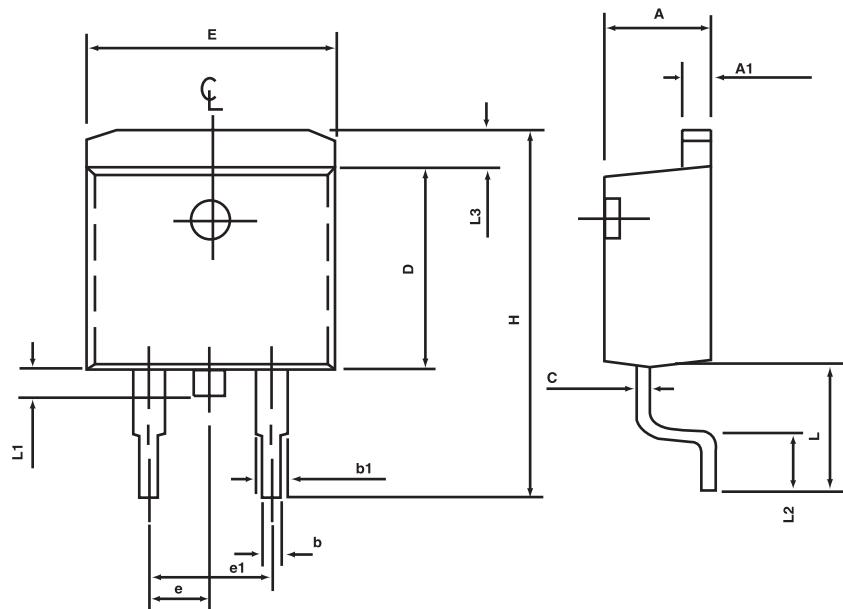
**TO-220**



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.32	4.80	0.170	0.189
B1	1.27	1.65	0.050	0.630
D	14.6	16.00	0.575	0.610
E	9.70	10.41	0.382	0.410
e	2.34	2.74	0.092	0.108
e1	4.68	5.48	0.184	0.216
F	1.14	1.40	0.045	0.055
H1	5.97	6.73	0.235	0.265
J1	2.20	2.79	0.087	0.110
L	12.88	14.22	0.507	0.560
L1	3.00	6.35	0.120	0.250
φP	3.50	3.94	0.138	0.155
Q	2.54	3.05	0.100	0.120

## PACKAGE OUTLINE DIMENSIONS

TO-263AB



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.70	0.169	0.185
A1	1.22	1.32	0.048	0.055
b	0.69	0.94	0.027	0.037
b1	1.22	1.40	0.048	0.055
C	0.36	0.56	0.014	0.022
D	8.64	9.652	0.340	0.380
E	9.70	10.54	0.382	0.415
e	2.29	2.79	0.090	0.110
e1	4.83	5.33	0.190	0.210
H	14.60	15.78	0.575	0.625
L	4.70	5.84	0.185	0.230
L1	1.20	1.778	0.047	0.070
L2	2.24	2.84	0.088	0.111
L3	1.40 MAX		0.055 MAX	

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TO-220/263AB Tube

